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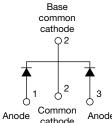
Vishay Semiconductors

HALOGEN

FREE

# Hyperfast Rectifier, 2 x 4 AFRED Pt®





D	PΑ	Κ	(TO-252	AA)
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com cath	
Anode Com	3 Anode

PRIMARY CHARACTERISTICS								
I <sub>F(AV)</sub>	2 x 4 A							
V <sub>R</sub>	200 V							
V <sub>F</sub> at I <sub>F</sub>	0.71 V							
t <sub>rr</sub> (typ.)	23 ns							
T <sub>J</sub> max.	175 °C							
Package	DPAK (TO-252AA)							
Circuit configuration	Common cathode							

### **FEATURES**

- · Hyperfast recovery time
- 175 °C max. operating junction temperature
- · Output rectification freewheeling
- Low forward voltage drop reduced Q<sub>rr</sub> and soft recovery
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **DESCRIPTION / APPLICATIONS**

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Peak repetitive reverse voltage	$V_{RRM}$		200	V					
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 164 °C	8	۸					
Non-repetitive peak surge current per leg	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	80	A					
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C					

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	200	-	-					
		I <sub>F</sub> = 4 A		0.87	0.95	V				
Conversed violations now loss	V <sub>F</sub>	I <sub>F</sub> = 8 A		0.95	1.10					
Forward voltage per leg		I <sub>F</sub> = 4 A, T <sub>J</sub> = 150 °C	-	0.71	0.80					
		I <sub>F</sub> = 8 A, T <sub>J</sub> = 150 °C	-	0.8	1.0					
		V <sub>R</sub> = V <sub>R</sub> rated	-	-	4					
Reverse leakage current per leg	I <sub>R</sub>	T <sub>J</sub> = 125 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	40	μA				
		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	80					
Junction capacitance per leg	C <sub>T</sub>	V <sub>R</sub> = 200 V	-	17	-	pF				
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8	-	nH				

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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 10$	$I_F = 1 \text{ A, } dI_F/dt = 100 \text{ A/}\mu\text{s, } V_R = 30 \text{ V}$			27			
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	20	-	ns		
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 4 A dI <sub>F</sub> /dt = 200 A/μs V <sub>B</sub> = 160 V	-	27	-			
Dools recovery oversent	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	2	-	^		
Peak recovery current		T <sub>J</sub> = 125 °C		-	3.4	-	- A		
Daviava va apvava v abava a	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	20	-	nC		
Reverse recovery charge		T <sub>J</sub> = 125 °C		-	46	-			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	TYP.	MAX.	UNITS							
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C				
Thermal resistance, per leg	R <sub>thJC</sub>		-	2.7	3.2	°C/W				
junction to case per device			-	1.35	1.6	C/W				
Annyayimata waisht				0.3		g				
Approximate weight				0.01		OZ.				
Marking device		Case style DPAK (TO-252AA)		8CWF	102FN					

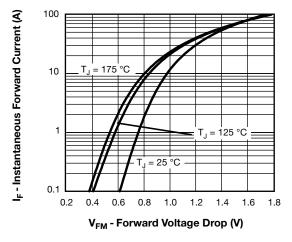


Fig. 1 - Typical Forward Voltage Drop Characteristics

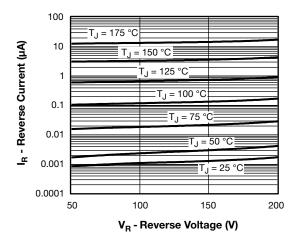


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

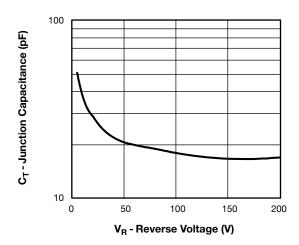


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

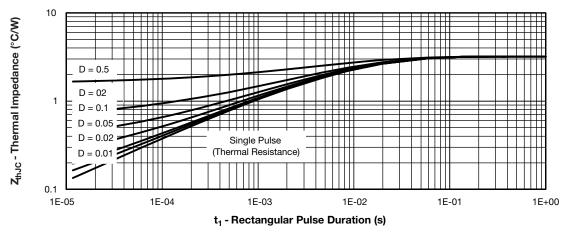


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

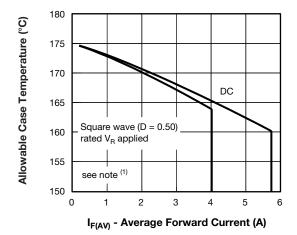


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

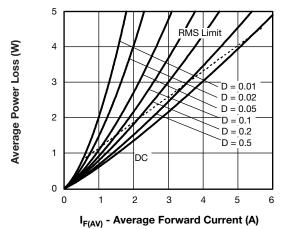


Fig. 6 - Forward Power Loss Characteristics

#### Note

(1) Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;  $Pd = forward power loss = I_{F(AV)} \times V_{FM} at (I_{F(AV)}/D)$  (see fig. 6);  $Pd_{REV} = inverse power loss = V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = rated V_R$ 

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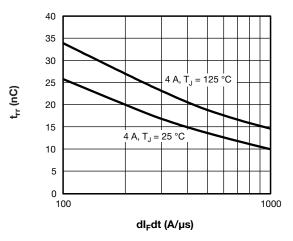


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

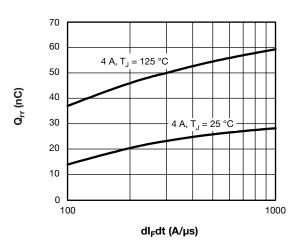


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

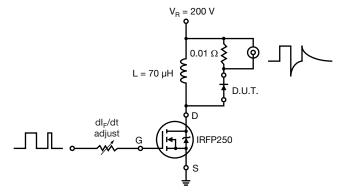
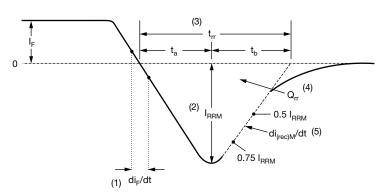


Fig. 9 - Reverse Recovery Parameter Test Circuit



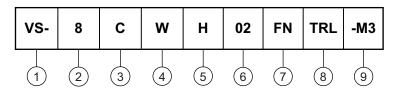
- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (4)  $Q_{rr}$  area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (2)  $\mathbf{I}_{\mathrm{RRM}}$  peak reverse recovery current
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (5)  $di_{(rec)M}/dt$  peak rate of change of current during  $t_b$  portion of  $t_{rr}$

Fig. 10 - Reverse Recovery Waveform and Definitions



### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Current rating (8 = 8 A)

3 - Circuit configuration:

C = common cathode

Package identifier:

W = D-PAK

5 - H = hyperfast recovery

6 - Voltage rating (02 = 200 V)

**7** - FN = TO-252AA

- • None = tube

• TR = tape and reel

• TRL = tape and reel (left oriented)

• TRR = tape and reel (right oriented)

9 - Environmental digit:

-M3 = halogen-free, RoHS-compliant and terminations lead (Pb)-free

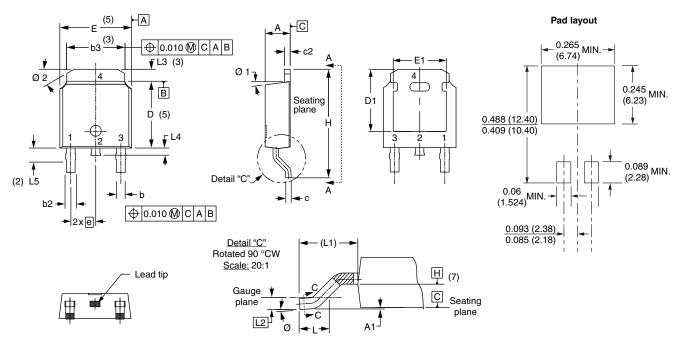
ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-8CWH02FN-M3	75	3000	Antistatic plastic tube						
VS-8CWH02FNTR-M3	2000	2000	13" diameter reel						
VS-8CWH02FNTRL-M3	3000	3000	13" diameter reel						
VS-8CWH02FNTRR-M3	3000	3000	13" diameter reel						

LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?95627					
Part marking information	www.vishay.com/doc?95176					
Packaging information	www.vishay.com/doc?95033					
SPICE model	www.vishay.com/doc?95375					



# D-PAK (TO-252AA) "M"

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES	
STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	0.020 BSC		
С	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
Е	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

#### **Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA

Revision: 24-Jun-16 1 Document Number: 95627

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